ABSTRACT

The present invention relates to a polishing apparatus having a plurality of polishing units (30A-30D). Moving mechanisms for moving top rings (301A~301D) between polishing positions on the polishing surfaces and wafer receiving/delivering positions are provided in each of the polishing units. Linear transporters (5, 6) are provided for transferring the wafer between a plurality of transferring positions (TP1-TP7) including the wafer receiving/delivering positions. Pushers (33, 34, 37, 38) for receiving and delivering the wafer between the linear transporters (5, 6) and the top rings (301A-301D) are provided at the transferring positions (TP2, TP3, TP6, TP7) as the wafer receiving/delivering positions.



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